

Certificate

Standard **ISO 50001:2018**

Certificate Registr. No. **01 407 2530750**

Certificate Holder: **Micron Technology, Inc.**
8000 South Federal Way
Boise ID 83707-0006
USA

Scope: Design, Research and Development, Manufacture, Assembly and Test of Semiconductor Memory Components, Module and SSD Products

Proof has been furnished by means of an audit that the requirements of ISO 50001:2018 are met.

Validity: The certificate is valid from 2025-09-24 until 2028-09-09.
First certification 2025

2025-11-21



TÜV Rheinland Cert GmbH
Am Grauen Stein · 51105 Köln

Annex to certificate

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No.	Location	Scope
/00	c/o Micron Technology, Inc. Global EHS 8000 South Federal Way Boise ID 83707 USA	Central Function for the Design, Research and Development, Manufacture, Assembly and Test of Memory Components, Module and SSD Products
/04	c/o Micron Semiconductor Asia Operations Pte. Ltd. 990 Bendemeer Road Singapore 339942 Singapore	Manufacturing and Testing of Memory Component, Module and SSD Products for Semiconductors
/05	c/o Micron Semiconductor (Xi'an) Co., Ltd. No.28-2, Xin Xi Avenue, High-tech Industries Development Zone, Xi'an 710119 Shaanxi P.R. China	Manufacture and Testing of Semiconductor Memory Components and Module Products
/06	c/o Micron Semiconductor Malaysia Sdn. Bhd. Tanjung Agas Industrial Area No K1-5, PLO 107 (PTD 6571) 84007 Muar, Johor Malaysia	Manufacturing and Testing of Semiconductor Components
/07	c/o Micron Semiconductor Asia Operations Pte. Ltd. 1 Woodlands Industrial Park D Singapore-Street 1 738799 Singapore	Manufacturing of Semiconductor Wafers

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/08	c/o Micron Semiconductor Asia Operations Pte. Ltd. 1 Northcoast Drive Singapore 757432 Singapore	Research and Development, Manufacturing and Testing of Semiconductor Wafers
/09	c/o Micron Memory Taiwan Co., Ltd. No. 369, Sec 4, Sanfong Road Taichung City TWN 42152 Taiwan, R.O.C.	Manufacturing and Testing of Semiconductor Wafers
/11	c/o Micron Memory Japan, K.K. 7-10 Yoshikawa Kogyo Danchi Higashi Hiroshima-shi Hiroshima, Hiroshima-ken 739-0198 Japan	Research and Development, Manufacturing and Testing of Semiconductor Wafers
/12	c/o Micron Technology Taiwan, Inc. No.667, Fuxing 3rd Rd. Hwa-Ya Technology Park Taoyuan City 333 Taiwan, R.O.C.	Manufacturing of Semiconductor Wafers
/13	c/o Micron Memory Taiwan Co., Ltd. (MTB) No. 88, Houke S. Rd., Houli Dist., Taichung City 42152 Taiwan, R.O.C.	Manufacturing and Testing of Semiconductor Module Products

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/15 c/o Micron Memory Malaysia Sdn Bhd
No. 1063, Plot 19
Tingkat Perusahaan 6
Prai Industrial Estate
13600 Prai, Penang
Malaysia

Manufacturing and Testing of Semiconductor Module and SSD Products

/16 c/o Micron Memory Malaysia Sdn. Bhd.
PMT 779, Lingkaran Cassia Selatan,
Taman Perindustrian Batu Kawan,
Bandar Cassia Mukim 13,
14100 Seberang Perai Selatan,
Pulau Pinang,
Malaysia

Manufacturing and Testing of Semiconductor Module, SSD Products and Component Assembly

2025-11-21



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